

ESD0524P

DESCRIPTION

The ESD0524P is a ultra-low capacitance Transient Voltage Suppressor (TVS) designed to protection for high-speed data interfaces. With typical capacitance of 0.2pF (I/O to I/O) only,

The ESD0524P is a designed to protect parasitic-sensitive systems against over-voltage and over-current transient events. It complies with IEC 61000-4-2 (ESD), Level 4($\pm 15\text{KV}$ air, $\pm 8\text{KV}$ contact discharge), IEC61000-4-4 (electrical fast transient-EFT) (40A, 5/50ns),very fast charged device model (CDM) ESD and cable discharge event(CDE), etc.

FEATURES

- ◇ Transient protection for high-speed data lines
IEC 61000-4-2(ESD) $\pm 25\text{KV}$ (Air)
 $\pm 20\text{KV}$ (Contact)
- IEC 61000-4-4(EFT)40A(5/50ns)
Cable Discharge Event(CDE)
- ◇ Package optimized for high-speed lines
- ◇ Ultra-small package(2.5mm*1.0mm*0.5mm)
- ◇ Protects four data lines
- ◇ Low capacitance: 0.2pF (I/O to I/O)
- ◇ Low leakage current
- ◇ Low clamping voltage
- ◇ Each I/O pin can withstand over 1000 ESD strikes for $\pm 8\text{KV}$ contact discharge

MACHANICAL DATA

- ◇ DFN2510 package
- ◇ Flammability Rating: UL 94V-0
- ◇ Terminal: Matte tin plated.
- ◇ Packaging: Tape and Reel
- ◇ High temperature soldering guaranteed: $260^{\circ}\text{C}/10\text{s}$
- ◇ Reel size: 7 inch

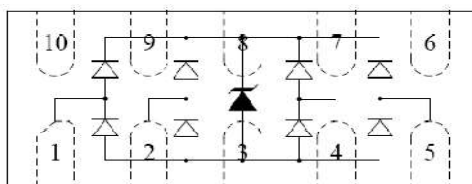
ORDERING INFORMATION

- ◇ Package: DFN2510
- ◇ Material: Halogen free
- ◇ Packing: Tape & Reel
- ◇ Quantity per reel: 3,000pcs

APPLICATIONS

- ◇ Serial ATA
- ◇ PCI Express
- ◇ Desktops, Servers and Notebooks
- ◇ MDDI Ports
- ◇ USB 2.0/3.0 Power and Data Line Protection
- ◇ Display Ports
- ◇ High Definition Multi-Media Interface (HDMI)
- ◇ Digital Visual Interface (DVI)

PIN CONFIGURATION



PACKAGE OUTLINE

| ABSOLUTE MAXIMUM RATING | | | |
|-------------------------|--|------------|-------|
| Symbol | Parameter | Value | Units |
| P _{PP} | Peak Pulse Power (8/20μs) | 60 | W |
| V _{ESD} | ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact) | ±25 ±20 | kV |
| T _{OPT} | Operating Temperature | -55/+125 | °C |
| T _{STG} | Storage Temperature | -55/+150 | °C |

| ELECTRICAL CHARACTERISTICS (T _{amb} =25°C) | | | | | | |
|---|---------------------------|---|-----|-----|-----|-------|
| Symbol | Parameter | Test Condition | Min | Typ | Max | Units |
| V _{RWM} | Reverse Working Voltage | Any I/O pin to GND | | | 5.0 | V |
| V _{BR} | Reverse Breakdown Voltage | I _T = 1mA Any I/O pin to GND | 6.0 | | 9.0 | V |
| I _R | Reverse Leakage Current | V _{RWM} = 5V Any I/O pin to GND | | | 1.0 | μA |
| V _C | Clamping Voltage | I _{PP} = 1A, t _p = 8/20μs Any I/O pin to GND | | | 10 | V |
| V _C | Clamping Voltage | I _{PP} = 4A, t _p = 8/20μs Any I/O pin to GND | | | 15 | V |
| C _{ESD} | Parasitic Capacitance | V _R = 0V, f = 1MHz Between I/O and GND | | 0.4 | 0.5 | pF |
| C _{ESD} | Parasitic Capacitance | V _R = 0V, f = 1MHz Between I/O and I/O | | 0.2 | 0.3 | pF |

Note: I/O pins are pin 1,2,4,5, GND pins are pin 3,8.

ELECTRICAL CHARACTERISTICS CURVE

Fig 1 Power Derating Curve

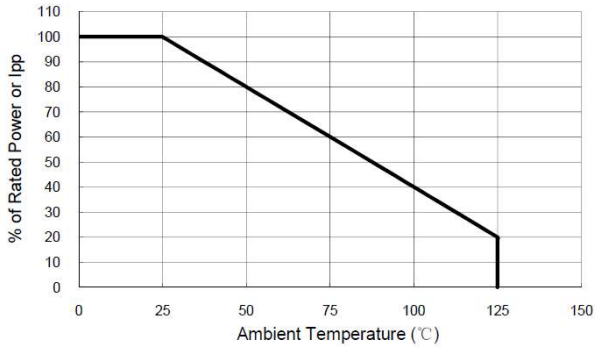


Fig 2 Clamping Voltage vs Peak Pulse Current

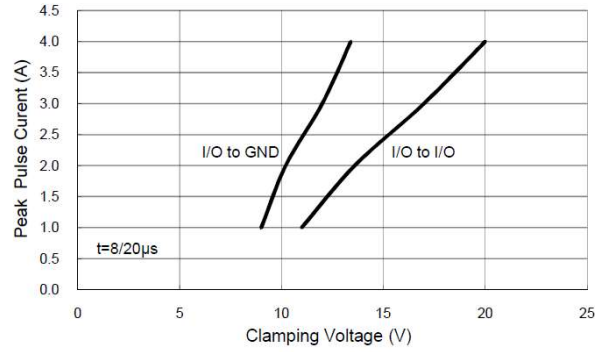


Fig 3 Voltage Sweeping of I/O to I/O

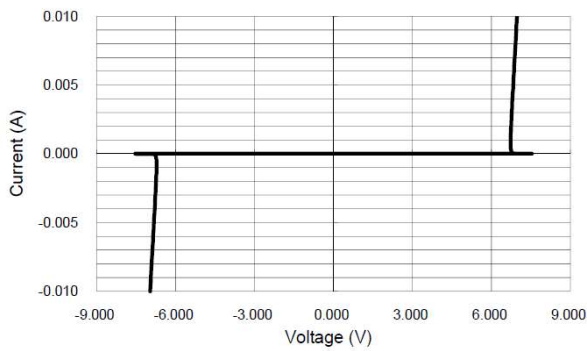
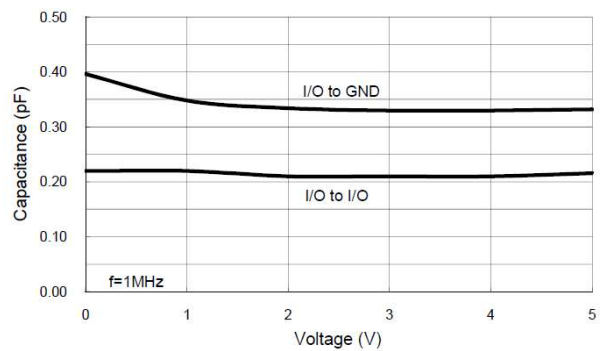
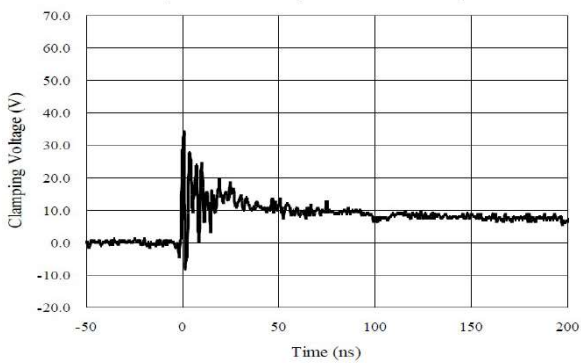


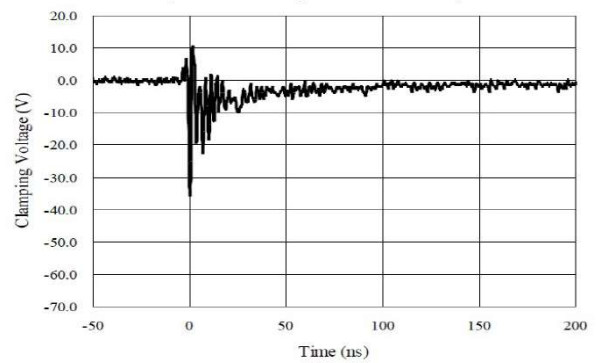
Fig 4 Voltage vs Capacitance



**Fig 5 ESD Clamping of I/O to GND
(+8kV Contact per IEC 61000-4-2)**

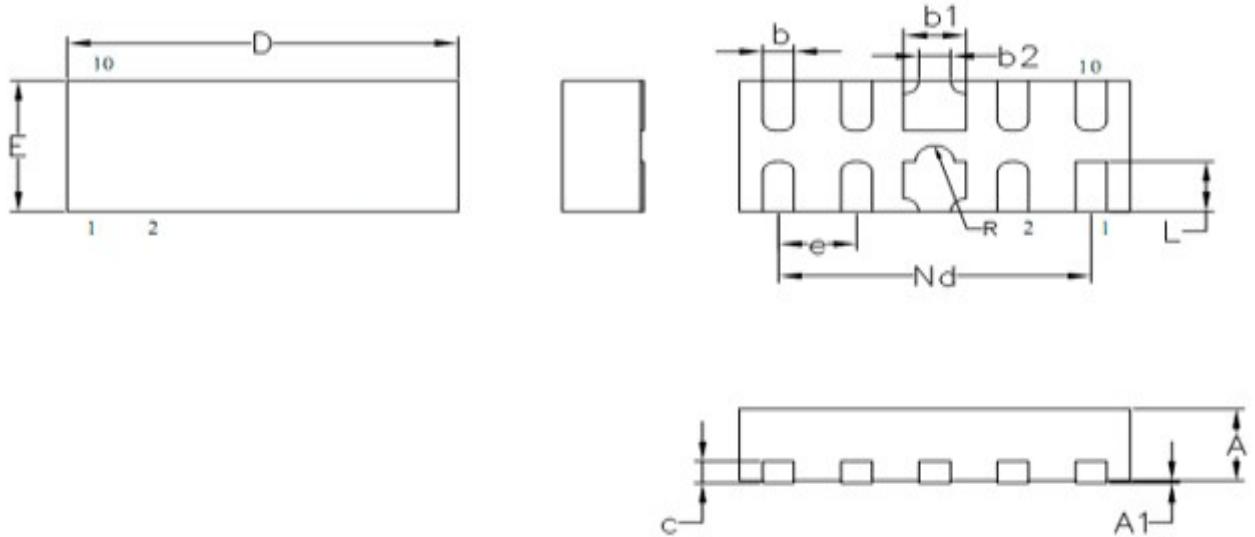


**Fig 6 ESD Clamping of I/O to GND
(-8kV Contact per IEC 61000-4-2)**



ESD0524P

DFN2510 PACKAGE OUTLINE DIMENSIONS



| Symbol | Dimensions (mm) | | |
|--------|-----------------|-------|------|
| | Min. | Nom. | Max. |
| D | 2.45 | 2.50 | 2.55 |
| E | 0.95 | 1.00 | 1.05 |
| b1 | 0.35 | 0.40 | 0.45 |
| b2 | 0.20REF | | |
| b | 0.15 | 0.20 | 0.25 |
| L | 0.33 | 0.38 | 0.43 |
| Nd | 2.00BSC | | |
| e | 0.50BSC | | |
| R | 0.10 | 0.125 | 0.15 |
| A | 0.45 | 0.50 | 0.55 |
| c | 0.15REF | | |
| A1 | 0.00 | - | 0.05 |